## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wen-chou Vincent Wang et al.

Attorney Docket No.: ALTRP096/A1201

Application No.: Please assign

Examiner: Unknown

Filed: Herewith

Group: Unknown

Title: STRUCTURE AND MATERIAL FOR ASSEMBLING A LOW-K SI DIE TO ACHIEVE A LOW WARPAGE AND INDUSTRIAL GRADE RELIABILITY FLIP CHIP PACKAGE WITH

ORGANIC SUBSTRATE

CERTIFICATE OF EXPRESS MAILINGI hereby certify that this paper and the documents and/or fees referred to as attached therein are being deposited with the United States Postal Service on November 20, 2003in an envelope as "Express Mail Post Office to Addressee" service under 37 CFR §1.10, Mailing Label Number EV 332826161 US, addressed to the Commissioner for Patents, P.Q. Box 1450 Alexandria, VA 22313

1450.

Ryan Eachus

## INFORMATION DISCLOSURE STATEMENT 37 CFR §§1.56 AND 1.97(b)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449 may be material to examination of the above-identified patent application. Applicants submit the list of these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application. Because the listed references were either cited by the PTO, or submitted to the PTO in the prior application, under 37 CFR § 1.98(d) Applicants submit that copies need not be provided.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office

Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. ALTRP096/A1202).

Respectfully submitted,
BEYER WEAVER & THOMAS, LLP

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Form 1449 (Modified)	Atty Docket No. Application No.:		
	ALTRP096/A1201	To be assigned	
Information Disclosure	Applicant:		
Statement By Applicant	Wen-chou Vincent Wang et al.		
	Filing Date	Group	
(Use Several Sheets if Necessary)	Herewith	Unknown	

## **U.S. Patent Documents**

Examiner						Sub-	Filing
Initial	No.	Patent No.	Date	Patentee	Class	class	Date
	Α						
	В						
	С						
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Foreign Patent or Published Foreign Patent Application

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Examiner		Document	Publication	Country or		Sub-	Trans	slation
Initial	No.	No.	Date	Patent Office	Class	class	Yes	No
	J							
	K					1		
	L							
	M						1	
	N						1	

## Other Documents

Examiner		
Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	0	U.S. Patent Application Serial No. 10/305,671 filed on November 25, 2002 entitled "Flip Chip Package With Warpage Control"
	P	
	Q	
Examiner	1	Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.